

CLAIMS

1. A compression-bond-connection substrate to be connected by compression-bonding to a compression-bonding target object having opposing-side terminals, comprising a compression-bonding-side surface to be connected to the compression-bonding target object, substrate-side terminals to be conductively connected to the opposing-side terminals, and backside wiring patterns formed on the reverse face of the compression-bonding-side surface, characterized in that step compensation patterns having substantially the same thickness as that of the backside wiring patterns are formed on the reverse face in positions corresponding to the backsides of the substrate-side terminals.

2. A compression-bond-connection substrate as stated in claim 1, characterized in that at least some of the step compensation patterns are formed on the reverse face in positions corresponding to the backsides of regions overlapping with a plurality of the substrate-side terminals.

3. A compression-bond-connection substrate as stated in claim 1, characterized in that the compression-bonding target object is an IC chip, and the opposing-side terminals

4. A compression-bond-connection substrate as stated in claim 1, characterized in that the compression-bonding target object is a substrate of a liquid crystal panel comprising a pair of substrates opposing each other and a liquid crystal sealed between the substrates, and the opposing-side terminals are external-connecting terminals formed on at least ~~either~~ one of the substrates.

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6. A liquid crystal device comprising a pair of substrates opposing each other, a liquid crystal sealed between the substrates, and a compression-bond-connection substrate to be connected at least to one of the pair of substrates, characterized in that the compression-bond-connection substrate is as stated in any one of claims 1 to 4.

as stated in ci

Add
H²

Ch 7